



## Material Content Data Sheet



<b>Sales Product Name</b>		ICE3AR4780JZ		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA001066062							
<b>Package</b>		PG-DIP-7-3		<b>Weight*</b>		645.07 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.649	0.57	0.57	5657	5657	
leadframe	inorganic material	phosphorus	7723-14-0	0.048	0.01		75		
	non noble metal	zinc	7440-66-6	0.194	0.03		300		
	non noble metal	iron	7439-89-6	3.872	0.60		6002		
wire	non noble metal	copper	7440-50-8	157.218	24.37	25.01	243723	250100	
	noble metal	gold	7440-57-5	0.418	0.06	0.06	649	649	
	encapsulation	organic material	carbon black	1333-86-4	2.349	0.36		3641	
plating	plastics	epoxy resin	-	63.418	9.83		98312		
	inorganic material	silicondioxide	60676-86-0	403.995	62.63	72.82	626284	728237	
	leadfinish	non noble metal	tin	7440-31-5	6.460	1.00	1.00	10014	10014
glue	noble metal	silver	7440-22-4	1.594	0.25	0.25	2471	2471	
*deviation	< 10%	plastics	epoxy resin	-	0.324	0.05		503	
		noble metal	silver	7440-22-4	1.528	0.24	0.29	2369	2872
Sum in total:						100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com